

Am9301

Demultiplexer/One-of-Ten Decoder

Distinctive Characteristics:

- 22 ns typical propagation delay
- Does not respond to codes above 9
- 100% reliability assurance testing in compliance with MIL-STD-883
- Can be used as one-of-eight decoder with active LOW enable

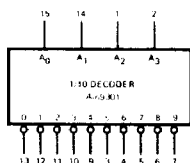
FUNCTIONAL DESCRIPTION

The Am9301 Demultiplexer/One-of-Ten Decoder accepts four active High BCD inputs and selects one-of-ten mutually exclusive active LOW outputs as shown in Truth Table II. The logic design of the 9301 insures that all outputs are HIGH (unselected) when binary codes greater than nine are applied to the inputs. The inputs A_0 , A_1 , A_2 , and A_3 of the 9301 correspond to the respective binary weight of 2^0 , 2^1 , 2^2 , and 2^3 .

Incoming data on input A_3 , can be demultiplexed to either of the eight outputs, zero through seven, with binary addressing at inputs A_0 , A_1 , and A_2 . This demultiplexing capability is illustrated in figure 5.

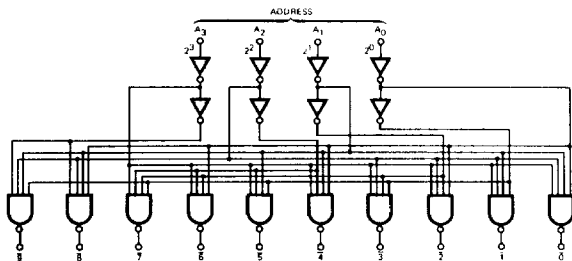
The most significant input, A_3 , produces an inhibit function when the 9301 is used as a 1-of-8 decoder with binary addressing at inputs A_0 , A_1 , and A_2 . The 1-of-32 decoder, in figure 6 illustrates the inhibit function.

LOGIC SYMBOL



V_{CC} = Pin 16
Gnd = Pin 8

LOGIC DIAGRAM

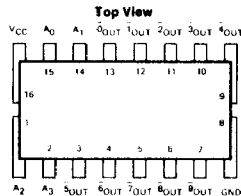


Am9301 ORDERING INFORMATION

Package Type	Temperature Range	Order Number
16-pin Molded DIP	0°C to +75°C	U7M930159X
16-pin Hermetic DIP	0°C to +75°C	U7B930159X
16-pin Hermetic DIP	55°C to +125°C	U7B930151X
16-pin Hermetic Flat Pack	55°C to +125°C	U4L930151X
Dice	Note	UXX9301XXD

Note: The dice supplied will contain units which meet both 0°C to +75°C and -55°C to +125°C temperature ranges.

CONNECTION DIAGRAM



NOTE: PIN 1 is marked for orientation.

MAXIMUM RATINGS

(Above which the useful life may be impaired)

Storage Temperature	-85°C to +150°C
Temperature (Ambient) Under Bias	-55°C to +125°C
Supply Voltage to Ground Potential (Pin 16 to Pin 8) Continuous	-0.5 V to +7 V
DC Voltage Applied to Outputs for High Output State	-0.5 V to +V _{CC} max
DC Input Voltage	-0.5 V to +5.5 V
Output Current, Into Outputs	30 mA
DC Input Current	-30 mA to +5.0 mA

ELECTRICAL CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (Unless Otherwise Noted)930150X T_A = 0°C to +75°CV_{CC} = 5.0 V ± 5%930151X T_A = -55°C to +125°CV_{CC} = 5.0 V ± 10%

Parameters	Description	Test Conditions	Min.	Typ. (Note 1)	Max.	Units
V _{OH}	Output HIGH Voltage	V _{CC} = MIN., I _{OH} = -0.8 mA V _{IN} = V _{IH} or V _{IL}	2.4	3.6		Volts
V _{OL}	Output LOW Voltage	V _{CC} = MIN., I _{OL} = 16.0 mA V _{IN} = V _{IH} or V _{IL}		0.2	0.4	Volts
V _{IH}	Input HIGH Level	Guaranteed input logical HIGH voltage for all inputs	2.0			Volts
V _{IL}	Input LOW Level	Guaranteed input logical LOW voltage for all inputs			0.8	Volts
I _{IL} (Note 2)	Unit Load Input LOW Current	V _{CC} = MAX., V _{IN} = 0.4 V		-1.0	-1.6	mA
I _{IH} (Note 2)	Unit Load Input HIGH Current	V _{CC} = MAX., V _{IN} = 2.4 V		6.0	40	μA
I _{SC}	Output Short Circuit Current	V _{CC} = MAX., V _{OUT} = 0.0 V	-20		-70	mA
I _{CC}	Power Supply Current	V _{CC} = MAX.		27 930151X 930150X	44 42	mA

Notes: 1) Typical limits are at V_{CC} = 5.0 V, 25°C ambient and maximum loading.

2) Actual input currents are obtained by multiplying unit load current by input load factor (see Loading Rules).

Switching Characteristics (+25°C)

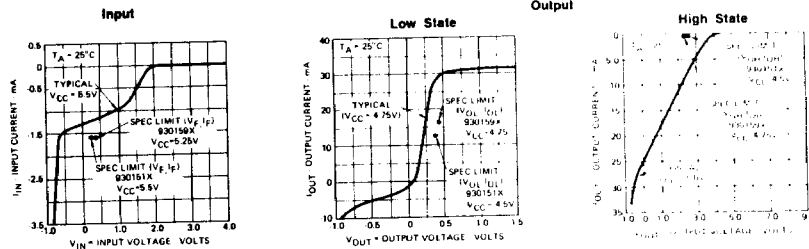
Parameters	Test Conditions	Min	Typ	Max	Units
t _{pd+} Turn Off Delay	V _{CC} = 5.0, C _L = 15 pF	10	23	35	ns
t _{pd-} Turn On Delay	Refer to figure 4.	10	20	30	ns

Note 1. Maximum current defined by DC Input Voltage.

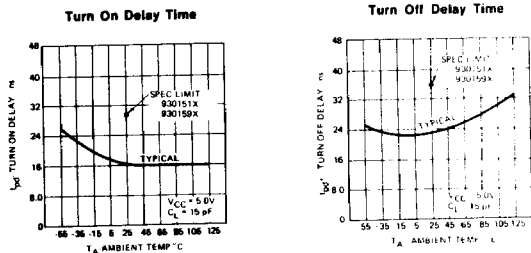
2. Pulse tested.

PERFORMANCE CURVES

Input/Output Characteristics



Switching Characteristics



DEFINITION OF TERMS

SUBSCRIPT TERMS:

H HIGH, applying to a HIGH-signal level or when used with V_{CC} to indicate high V_{CC} value.

I Input.

L LOW, applying to a LOW signal level or when used with V_{CC} to indicate low V_{CC} value.

O Output.

FUNCTIONAL TERMS:

BCD Binary coded decimal notation represents each of the ten decimal digits by a code consisting of a group of four (4) binary digits.

Decoder/Demultiplexer On the basis of an applied instruction, channels of communication are selected which connect certain sources of information to certain destinations e.g., the distribution of timing signals; the interconnection between arithmetic registers.

Fan-Out The logic HIGH or LOW output drive capability in terms of Input Unit Loads.

Unit load One TTL gate input load. In the HIGH state it is equal to 40 μA at 2.4V and in the LOW state it is equal to -1.6mA at 0.4V.

OPERATIONAL TERMS:

I_{OH} Output HIGH current, forced out of output in V_{OH} test.

I_{OL} Output LOW current, forced into output in V_{OL} test.

I_{CC} The current drawn by the device under a +5.0 V power supply, bias input terminals grounded and output terminals open.

Negative Current Current flowing out of the device.

Positive Current Current flowing into the device.

V_{IH} Minimum logic HIGH input voltage.

V_{IL} Maximum logic LOW input voltage.

V_{OH} Minimum logic HIGH output voltage with output HIGH current I_{OH} flowing out of output.

V_{OL} Maximum logic LOW output voltage with output LOW current I_{OL} into output.

SWITCHING TERMS: (All switching times are measured at the 1.5V logic level).

t_{pd+} The propagation delay measured from the input address transition to a corresponding output signal LOW-HIGH transition.

t_{pd-} The propagation delay measured from the input address transition to a corresponding output signal HIGH-LOW transition. 2-43

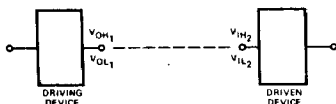
Interfacing Digital Family	Equivalent Input Unit Load	
	HIGH	LOW
Advanced Micro Devices 9300/2500 Series	1	1
FSC Series 9300	1	1
Advanced Micro Devices 54/7400 Series	1	1
TI Series 54/7400	1	1
Signetics Series 8200	2	2
National Series DM 75/85	1	1
DTL Series 930	12	1

[illegible]

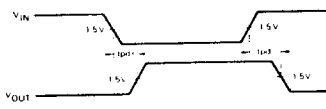
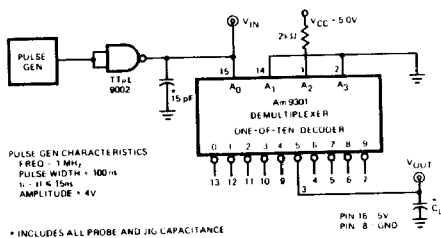
L = LOW Logic Level

Input/Output	Pin No.'s	Input Unit Load	Fanout	
			Output HIGH	Output LOW
A ₂	1	1	—	—
A ₃	2	1	—	—
5 _{OUT}	3	—	20	10
6 _{OUT}	4	—	20	10
7 _{OUT}	5	—	20	10
8 _{OUT}	6	—	20	10
9 _{OUT}	7	—	20	10
GND	8	—	—	—
4 _{OUT}	9	—	20	10
3 _{OUT}	10	—	20	10
2 _{OUT}	11	—	20	10
1 _{OUT}	12	—	20	10
0 _{OUT}	13	—	20	10
A ₁	14	1	—	—
A ₀	15	1	—	—
V _{CC}	16	—	—	—

Figure 1 is a graph showing output/input voltage levels in volts versus driving and driven devices. The y-axis is labeled "OUTPUT/INPUT VOLTAGE LEVELS - VOLTS" and ranges from 0.0 to 3.0 in increments of 0.2. The x-axis is divided into two sections: "DRIVING DEVICE" on the left and "DRIVEN DEVICE" on the right, separated by a vertical line. The graph is divided into four quadrants by this vertical line and two horizontal dashed lines. The top-left quadrant is labeled "MINIMUM LOGIC 'HIGH' OUTPUT VOLTAGE" with V_{OH1} on the right. The top-right quadrant is labeled "MINIMUM LOGIC 'HIGH' INPUT VOLTAGE" with V_{IH2} on the left. The bottom-left quadrant is labeled "MAXIMUM LOGIC 'LOW' OUTPUT VOLTAGE" with V_{OL1} on the right. The bottom-right quadrant is labeled "MAXIMUM LOGIC 'LOW' INPUT VOLTAGE" with V_{IL2} on the left. Two shaded rectangular regions represent "NOISE IMMUNITY". One region is in the top-left quadrant, labeled "NOISE IMMUNITY (High level)". The other region is in the bottom-left quadrant, labeled "NOISE IMMUNITY (Low level)".

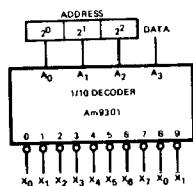


SWITCHING TIME TEST CIRCUITS & WAVEFORMS



BASIC DEMULTIPLEXER/DECODER APPLICATIONS

DIGITAL DEMULTIPLEXER



ADDRESS			OUTPUT LINE
A ₀	A ₁	A ₂	
0	0	0	0
1	0	0	1
0	1	0	2
1	1	0	3
0	0	1	4
1	0	1	5
0	1	1	6
1	1	1	7

Data may be routed from a source to any of eight (0-7) outputs by addressing that output. The seven non-addressed outputs remain clear.

Figure 5

ADDITIONAL APPLICATIONS

ONE-OUT-OF-THIRTY-TWO DECODER

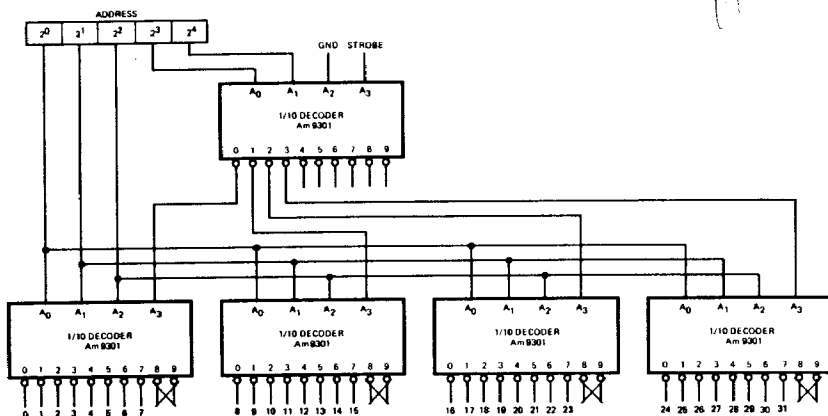
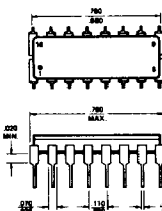


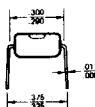
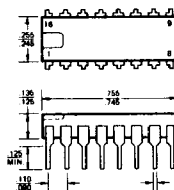
Figure 6

Hermetic

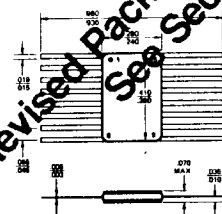


PHYSICAL DIMENSIONS Dual-In-Line

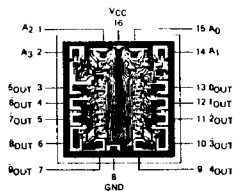
Molded



Flat Pack



Metalization and Pad Layout



76 x 78 Mils

ADVANCED
MICRO
DEVICES INC.
901 Thompson Place
Sunnyvale
California 94086
(408) 732-2400
TWX: 910-339-9260
TELEX: 34-6306

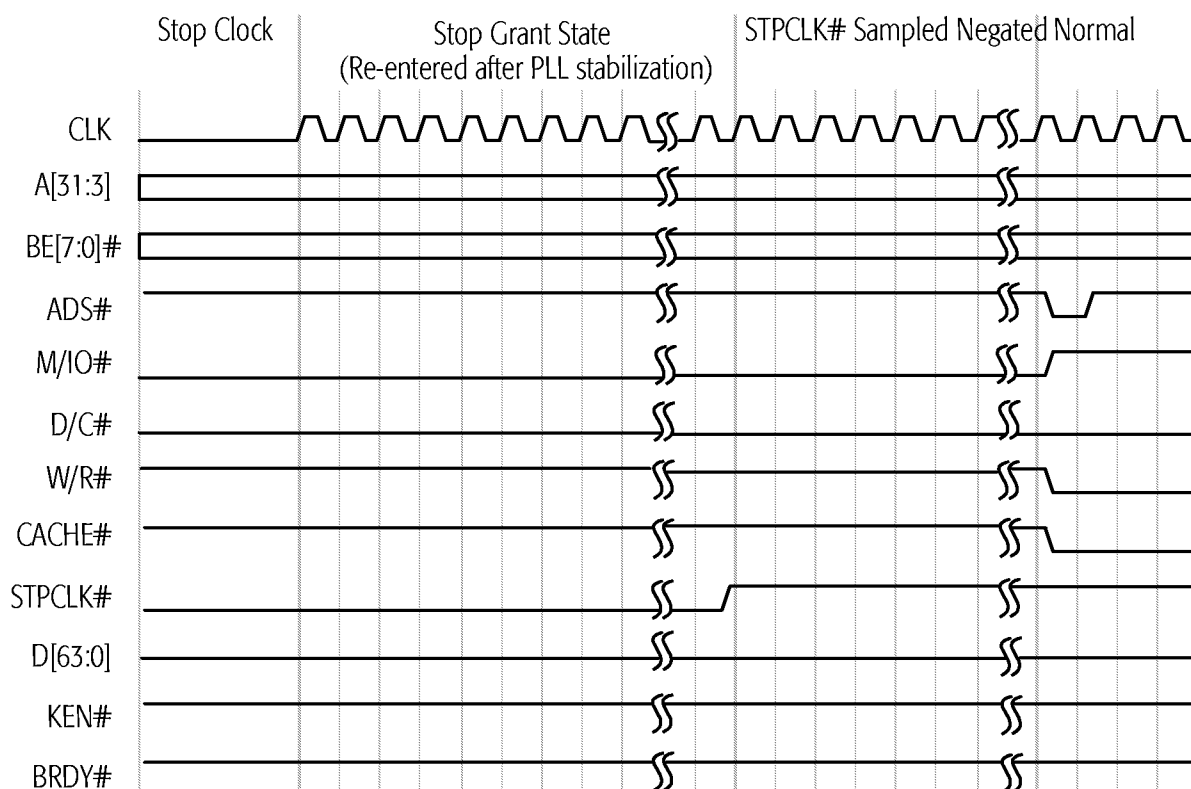


Figure 75. Stop Grant and Stop Clock Modes, Part 2

**INIT-Initiated
Transition from
Protected Mode to
Real Mode**

INIT is typically asserted in response to a BIOS interrupt that writes to an I/O port. This interrupt is often in response to a Ctrl-Alt-Del keyboard input. The BIOS writes to a port (similar to port 64h in the keyboard controller) that asserts INIT. INIT is also used to support 80286 software that must return to Real mode after accessing extended memory in Protected mode.

The assertion of INIT causes the processor to empty its pipelines, initialize most of its internal state, and branch to address FFFF_FFF0h—the same instruction execution starting point used after RESET. Unlike RESET, the processor preserves the contents of its caches, the floating-point state, the MMX state, Model-Specific Registers (MSRs), the CD and NW bits of the CR0 register, the time stamp counter, and other specific internal resources.

Figure 76 shows an example in which the operating system writes to an I/O port, causing the system logic to assert INIT. The sampling of INIT asserted starts an extended microcode sequence that terminates with a code fetch from FFFF_FFF0h, the reset location. INIT is sampled on every clock edge but is not recognized until the next instruction boundary. During an I/O write cycle, it must be sampled asserted a minimum of three clock edges before BRDY# is sampled asserted if it is to be recognized on the boundary between the I/O write instruction and the following instruction. If INIT is asserted synchronously, it can be asserted for a minimum of one clock. If it is asserted asynchronously, it must have been negated for a minimum of two clocks, followed by an assertion of a minimum of two clocks.

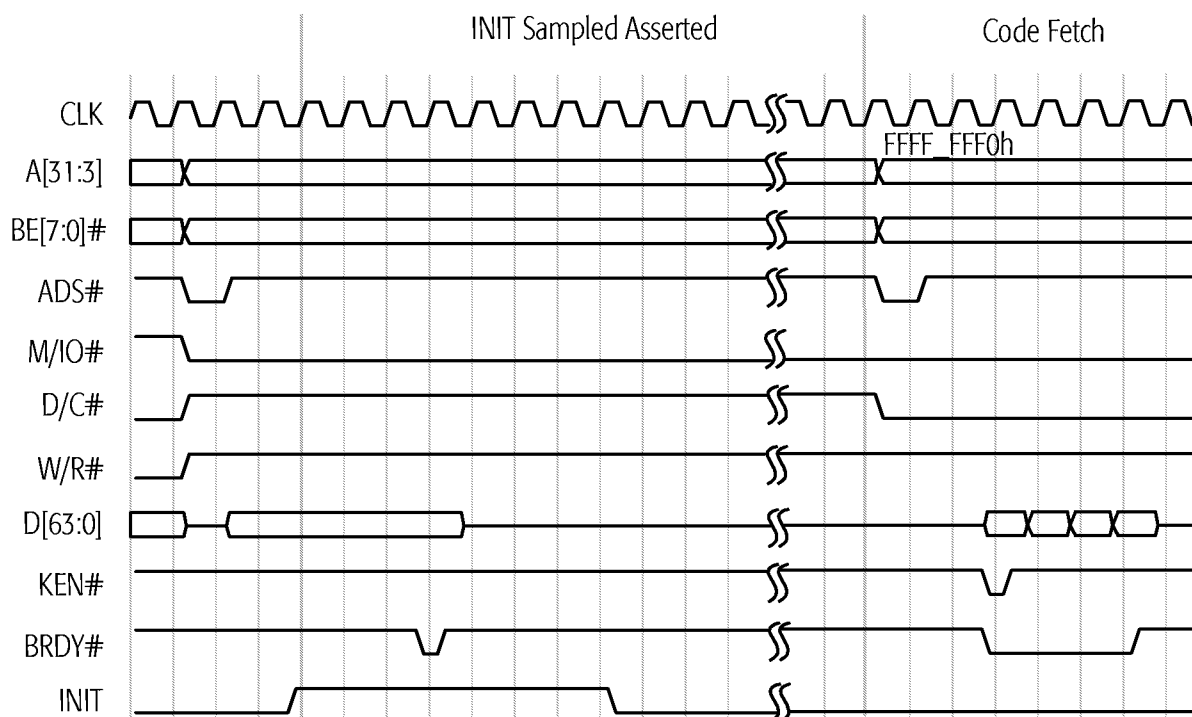


Figure 76. INIT-Initiated Transition from Protected Mode to Real Mode

6 Power-on Configuration and Initialization

On power-on the system logic must reset the AMD-K6-2 processor by asserting the RESET signal. When the processor samples RESET asserted, it immediately flushes and initializes all internal resources and its internal state, including its pipelines and caches, the floating-point state, the MMX and 3DNow! states, and all registers. Then the processor jumps to address FFFF_FFF0h to start instruction execution.

6.1 Signals Sampled During the Falling Transition of RESET

- FLUSH#** FLUSH# is sampled on the falling transition of RESET to determine if the processor begins normal instruction execution or enters Tri-State Test mode. If FLUSH# is High during the falling transition of RESET, the processor unconditionally runs its Built-In Self Test (BIST), performs the normal reset functions, then jumps to address FFFF_FFF0h to start instruction execution. (See “Built-In Self-Test (BIST)” on page 217 for more details.) If FLUSH# is Low during the falling transition of RESET, the processor enters Tri-State Test mode. (See “Tri-State Test Mode” on page 218 and “FLUSH# (Cache Flush)” on page 103 for more details.)
- BF[2:0]** The internal operating frequency of the processor is determined by the state of the bus frequency signals BF[2:0] when they are sampled during the falling transition of RESET. The frequency of the CLK input signal is multiplied internally by a ratio defined by BF[2:0]. (See “BF[2:0] (Bus Frequency)” on page 92 for the processor-clock to bus-clock ratios.)
- BRDYC#** BRDYC# is sampled on the falling transition of RESET to configure the drive strength of A[20:3], ADS#, HITM#, and W/R#. If BRDYC# is Low during the fall of RESET, these outputs are configured using higher drive strengths than the standard strength. If BRDYC# is High during the fall of RESET, the standard strength is selected. (See “BRDYC# (Burst Ready Copy)” on page 95 for more details.)

6.2 RESET Requirements

During the initial power-on reset of the processor, RESET must remain asserted for a minimum of 1.0 ms after CLK and V_{CC} reach specification. (See “CLK Switching Characteristics” on page 255 for clock specifications. See “Electrical Data” on page 247 for V_{CC} specifications.)

During a warm reset while CLK and V_{CC} are within specification, RESET must remain asserted for a minimum of 15 clocks prior to its negation.

6.3 State of Processor After RESET

Output Signals

Table 31 shows the state of all processor outputs and bidirectional signals immediately after RESET is sampled asserted.

Table 31. Output Signal State After RESET

Signal	State	Signal	State
A[31:3], AP	Floating	LOCK#	High
ADS#, ADSC#	High	M/IO#	Low
APCHK#	High	PCD	Low
BE[7:0]#	Floating	PCHK#	High
BREQ	Low	PWT	Low
CACHE#	High	SCYC	Low
D/C#	Low	SMIACK#	High
D[63:0], DP[7:0]	Floating	TDO	Floating
FERR#	High	VCC2DET	Low
HIT#	High	VCC2H/L#	Low
HITM#	High	W/R#	Low
HLDA	Low	—	—

Registers

Table 32 on page 175 shows the state of all architecture registers and Model-Specific Registers (MSRs) after the processor has completed its initialization due to the recognition of the assertion of RESET.